



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BGSX 33MU16 E6327	<b>Issued</b>	11. August 2021
<b>MA#</b>	MA005415667		
<b>Package</b>	PG-ULGA-16-3	<b>Weight*</b>	5.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.917	17.00	17.00	170024	170024
bumps	non noble metal	copper	7440-50-8	0.028	0.52	0.52	5188	5188
encapsulation	organic material	carbon black	1333-86-4	0.014	0.27		2688	
	plastics	epoxy resin	-	0.326	6.05		60491	
	inorganic material	silicondioxide	60676-86-0	2.075	38.47	44.79	384904	448083
plating	noble metal	palladium	7440-05-3	0.000	0.01		54	
	noble metal	gold	7440-57-5	0.000	0.01		87	
	non noble metal	nickel	7440-02-0	0.009	0.16	0.18	1590	1731
solder	noble metal	silver	7440-22-4	0.000	0.01		51	
	non noble metal	tin	7440-31-5	0.015	0.28	0.29	2772	2823
ubm	non noble metal	tungsten	7440-33-7	0.000			4	
	non noble metal	titanium	7440-32-6	0.000			7	
	non noble metal	copper	7440-50-8	0.000			20	31
solder resists	inorganic material	magnesiumsilicate	1343-88-0	0.003	0.06		573	
	plastics	epoxy resin	-	0.010	0.18		1792	
	inorganic material	silicondioxide	60676-86-0	0.010	0.19		1864	
	inorganic material	bariumsulfate	7727-43-7	0.016	0.29	0.72	2939	7168
substrate metal	non noble metal	copper	7440-50-8	0.801	14.86	14.86	148583	148583
substrate plastic	inorganic material	glass fibre wool	65997-17-3	0.525	9.74		97366	
	organic material	thermosetting resin	-	0.642	11.90	21.64	119003	216369
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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